

SBAS256A – DECEMBER 2002 – AUGUST 2007

16-Bit, Single Channel DIGITAL-TO-ANALOG CONVERTER With Internal Reference and Parallel Interface

FEATURES

- LOW POWER: 150mW Maximum
- +10V INTERNAL REFERENCE
- UNIPOLAR OR BIPOLAR OPERATION
- SETTLING TIME: 5µs to ±0.003% FSR
- 16-BIT MONOTINICITY, -40°C TO +85°C
- ±10V, ±5V OR +10V CONFIGURABLE VOLTAGE OUTPUT
- RESET TO MIN-SCALE OR MID-SCALE
- DOUBLE-BUFFERED DATA INPUT
- INPUT REGISTER DATA READBACK
- **SMALL LQFP-48 PACKAGE**
- SUPPORTS TRANSPARENT DATA INPUT OPERATION

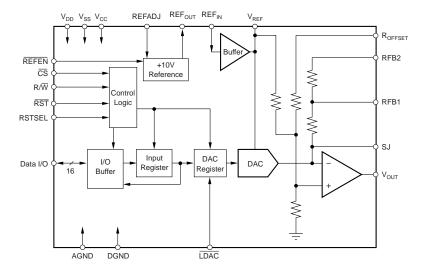
APPLICATIONS

- PROCESS CONTROL
- ATE PIN ELECTRONICS
- CLOSED-LOOP SERVO CONTROL
- MOTOR CONTROL
- DATA ACQUISITION SYSTEMS

DESCRIPTION

The DAC7742 is a 16-bit Digital-to-Analog Converter (DAC) that provides 16 bits of monotonic performance over the specified operating temperature range and offers a +10V, low-drift internal reference. Designed for automatic test equipment and industrial process control applications, the DAC7742 output swing can be configured in a $\pm 10V$, $\pm 5V$, or +10V range. The flexibility of the output configuration allows the DAC7742 to provide both unipolar and bipolar operation by pin strapping. The DAC7742 includes a high-speed output amplifier with a maximum settling time of $5\mu s$ to $\pm 0.003\%$ FSR for a 20V full-scale change and only consumes 100mW (typical) of power.

The DAC7742 features a standard 16-bit parallel interface with double buffering to allow asynchronous updates of the analog output, and data read-back to support data integrity verification prior to an update. A user-programmable reset control allows the DAC output to reset to min-scale (FFFF_H) or mid-scale (7FFF_H) overriding the DAC register values. The DAC7742 is available in an LQFP-48 package and three performance grades specified to operate from –40°C to +85°C.





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ABSOLUTE MAXIMUM RATINGS(1)

NOTE: (1) Stresses above those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

PRODUCT	LINEARITY ERROR (LSB)	DIFFERENTIAL NONLINEARITY (LSB)	PACKAGE-LEAD	PACKAGE DESIGNATOR ⁽¹⁾	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	TRANSPORT MEDIA, QUANTITY
DAC7742	±6 "	±4 "	LQFP-48	PT "	-40°C to +85°C	DAC7742Y/250 DAC7742Y/2K	DAC7742Y	Tape and Reel, 250 Tape and Reel, 2000
DAC7742	±4 "	<u>±2</u> "	LQFP-48	PT "	–40°C to +85°C	DAC7742YB/250 DAC7742YB/2K	DAC7742YB	Tape and Reel, 250 Tape and Reel, 2000
DAC7742	±3	±1 "	LQFP-48	PT "	-40°C to +85°C	DAC7742YC/250 DAC7742YC/2K	DAC7742YC	Tape and Reel, 250 Tape and Reel, 2000

NOTE: (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

ELECTRICAL CHARACTERISTICS

All specifications at T_A = T_{MIN} to T_{MAX}, V_{CC} = +15V, V_{SS} = -15V, V_{DD} = +5V, Internal reference enabled, unless otherwise noted.

			DAC7742Y	1	С	AC7742Y	В		DAC7742Y	С	
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
ACCURACY											
Linearity Error (INL)				±6			±4			±3	LSB
	T _A = 25°C			±5			±3			±2	LSB
Differential Linearity Error (DNL)				±4			±2			±1	LSB
Monotonicity		14			15			16			Bits
Offset Error				±0.1			*			*	% of FSR
Offset Error Drift			±2			*			*		ppm/°C
Gain Error	With Internal REF			±0.4			±0.25			±0.2	% of FSR
	With External REF			±0.25			±0.1			*	% of FSR
Gain Error Drift	With Internal REF		±15			±10			±7		ppm/°C
PSRR (V _{CC} or V _{SS})	At Full-Scale		50	200		*	*		*	*	ppm/V
ANALOG OUTPUT(1)											
Voltage Output ⁽²⁾	+11.4/-4.75		0 to 10			*			*		V
	+11.4/-11.4		±10			*			*		V
	+11.4/-6.4		±5			*			*		V
Output Current		±5			*			*			mA
Output Impedance			0.1			*			*		Ω
Maximum Load Capacitance			200			*			*		pF
Short-Circuit Current			±15			*			*		mA
Short-Circuit Duration	AGND		Indefinite			*			*		
REFERENCE											
Reference Output		9.96	10	10.04	9.975	*	10.025	*	*	*	V
REF _{OUT} Impedance			400			*			*		Ω
REF _{OUT} Voltage Drift			±15			±10			±7		ppm/°C
REF _{OUT} Voltage Adjustment ⁽³⁾		±25			*			*			mV
REF _{IN} Input Range ⁽⁴⁾		4.75		V _{CC} - 1.4	*		*	*		*	V
REF _{IN} Input Current			10			*			*		nA
REFADJ Input Range	Absolute Max Value that	0		10	*		*	*		*	V
	can be applied is V _{CC}										
REFADJ Input Impedance			50			*			*		kΩ
V _{REF} Output Current		-2		+2	*		*	*		*	mA
V _{REF} Impedance			1			*			*		Ω



ELECTRICAL CHARACTERISTICS (Cont.)

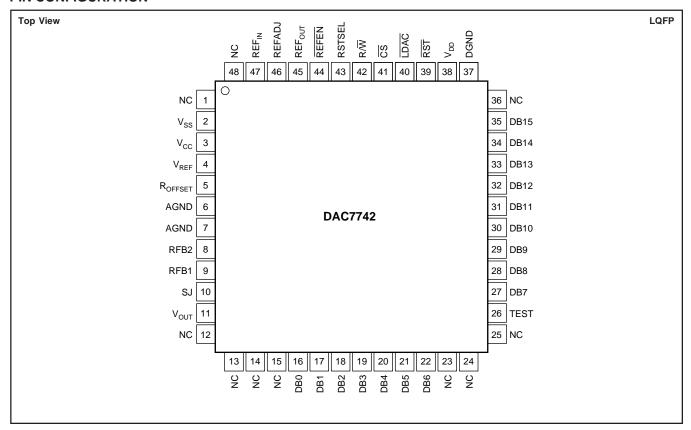
All specifications at $T_A = T_{MIN}$ to T_{MAX} , $V_{CC} = +15V$, $V_{SS} = -15V$, $V_{DD} = +5V$, Internal reference enabled, unless otherwise noted.

			OAC7742	Y		DAC7742Y	′B	ı	DAC7742Y	С	
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
DYNAMIC PERFORMANCE											
Settling Time to ±0.003%	20V Output Step		3	4		*	*		*	*	μs
	$R_L = 5k\Omega$, $C_L = 200pF$,										
	with external REF _{OUT}										
	to REF _{IN} filter ⁽⁵⁾										
Digital Feedthrough			2			*			*		nV-s_
Output Noise Voltage	at 10kHz		100			*			*		nV/√Hz
DIGITAL INPUT											
V _{IH}	I _H < 10μΑ	0.7 • V _{DD}			*			*			V
V _{IL}	I _L < 10μΑ			0.3 • V _{DD}			*			*	V
Input Coding		S	ee Table	İII		*			*		
DIGITAL OUTPUT											
V _{OH}	$I_{OH} = -0.8 \text{mA}$	3.6			*			*			V
V _{OL}	$I_{OL} = 1.6 \text{mA}$			0.4			*			*	V
POWER SUPPLY											
V_{DD}		+4.75	+5.0	+5.25	*	*	*	*	*	*	V
V _{CC}		+11.4		+15.75	*		*	*		*	V
V _{SS}	Bipolar Operation	-15.75		-11.4	*		*	*		*	V
	Unipolar Operation	-15.75		-4.75	*		*	*		*	V
I _{DD}			100			*			*		μΑ
Icc	Unloaded		4	6		*	*		*	*	mA
I _{ss}	Unloaded	-4	-2.5		*	*		*	*		mA
Power	No Load, Ext. Reference		85			*			*		mW
	No Load, Int. Reference		100	150		*	*		*	*	mW
TEMPERATURE RANGE											
Specified Performance		-40		+85	*		*	*		*	°C

^{*} Specifications same as DAC7742Y.

NOTES: (1) With minimum V_{CC}/V_{SS} requirements, internal reference enabled. (2) Please refer to the "Theory of Operation" section for more information with respect to output voltage configurations. (3) See Figure 7 for gain and offset adjustment connection diagrams when using the internal reference. (4) The minimum value for REF_{IN} must be equal to the greater of V_{SS} +14V and +4.75V, where +4.75V is the minimum voltage allowed. (5) Reference low-pass filter values: 100k Ω , 1.0 μ F (See Figure 10).

PIN CONFIGURATION



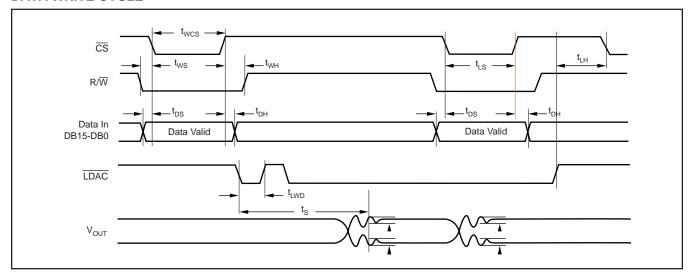
PIN DESCRIPTIONS

PIN	NAME	DESCRIPTION	PIN	NAME	DESCRIPTION
1	NC	No Connection	28	DB8	Data Bit 8
2	V _{SS}	Negative Analog Power Supply		DB9	Data Bit 9
3	V _{CC}	Positive Analog Power Supply	30	DB10	Data Bit 10
4	V _{REF}	Buffered Output from REF _{IN} ; can be used to	31	DB11	Data Bit 11
	KEF	drive external devices. Internally, this pin	32	DB12	Data Bit 12
		directly drives the DAC's circuitry.	33	DB13	Data Bit 13
5	R _{OFFSET}	Offsetting Resistor	34	DB14	Data Bit 14
6	AGND	Analog Ground (Must be tied to analog ground.)	35	DB15	Data Bit 15 (MSB)
7	AGND	Analog Ground (Must be tied to analog ground.)	36	NC	No Connection
8	RFB2	Feedback Resistor 2, used to configure DAC	37	DGND	Digital Ground
		output range.	38	V_{DD}	Digital Power Supply
9	RFB1	Feedback Resistor 1, used to configure DAC	39	RST	V _{OUT} reset; active LOW, depending on the state of
10	SJ	output range.			RSTSEL, the DAC register is either reset to mid-
11		Summing Junction of the Output Amplifier DAC Voltage Output	40	LDAC	scale or min-scale.
12	V _{OUT} NC	No Connection	40	LDAC	DAC register load control, active LOW. Data is loaded from the input register to the DAC register.
13	NC NC	No Connection	41	c s	Chip Select, Active LOW
14	NC NC	No Connection	42	R/W	Enabled by CS, controls data read (HIGH) and
15	NC NC	No Connection	1	1077	write (LOW) from or to the input register.
16	DB0	Data Bit 0 (LSB)	43	RSTSEL	Reset Select; determines the action of RST. If
17	DB0 DB1	Data Bit 0 (LSB)			HIGH, RST will reset the DAC register to mid-
18	DB1	Data Bit 1			scale. If LOW, RST will reset the DAC register to
19	DB2	Data Bit 3	44	REFEN	min-scale.
20	DB3	Data Bit 4	44	KEFEN	Enables internal +10V reference (REF _{OUT}), active LOW.
21	DB5	Data Bit 5	45	REFOUT	Internal Reference Output
22	DB6	Data Bit 6	46	REFADJ	Internal Reference Trim. (Acts as a gain
23	NC NC	No Connection	"	I TELL TIES	adjustment input when the internal reference is
24	NC NC	No Connection			used.)
25	NC NC	No Connection	47	REF _{IN}	Reference Input
26	TEST	Reserved, Connect to DGND	48	NC	No Connection
27	DB7	Data Bit 7			
	557	Data Dit 7			

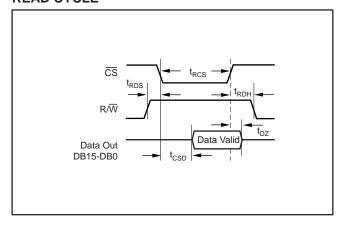


TIMING DIAGRAMS

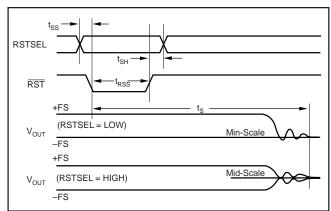
DATA WRITE CYCLE



READ CYCLE



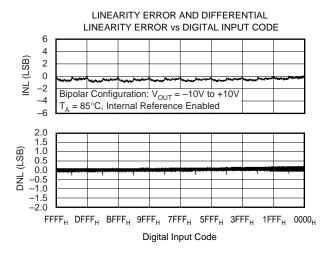
RESET TIMING

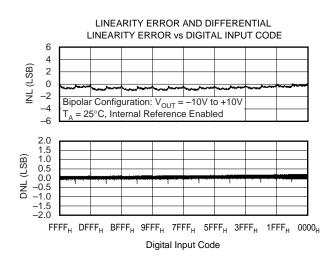


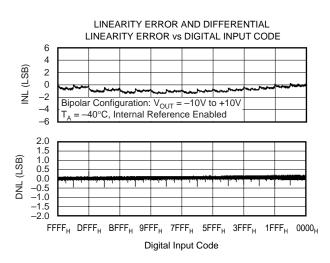
TIMING CHARACTERISTICS

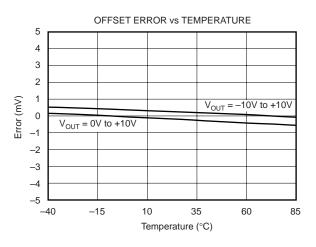
			DAC7742Y		
PARAMETER	DESCRIPTION	MIN	TYP	MAX	UNITS
READ					
t _{RCS}	CS LOW for Read	90			ns
t _{RDS}	R/W HIGH to CS LOW	10			ns
t _{RDH}	R/W HIGH After CS HIGH	10			ns
t _{DZ}	CS HIGH to Data Bus High Impedance	10		70	ns
t _{CSD}	CS LOW to Data Bus Valid		70	100	ns
WRITE					
t _{WS}	R/W LOW to CS LOW	10			ns
t _{WH}	R/W LOW After CS HIGH	10			ns
t _{wcs}	CS LOW for Write	25			ns
t _{LWD}	LDAC LOW for Write	20			ns
t _{LS}	CS LOW to LDAC HIGH for Direct Update	30			ns
t _{LH}	CS LOW After LDAC HIGH	0			ns
t _{DS}	Data Valid to CS LOW	0			ns
t _{DH}	Data Valid After CS HIGH	20			ns
RESET					
t _{RSS}	RST LOW	30			ns
t _{SS}	RSTSEL Valid Before RST LOW	0			ns
t _{SH}	RSTSEL Valid After RST HIGH	10			ns
ANALOG					
t _S	Voltage Output Settling Time			5	μs

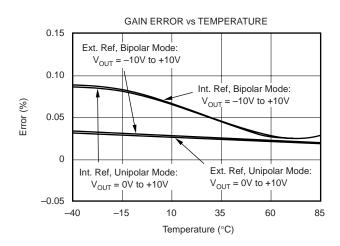
TYPICAL CHARACTERISTICS

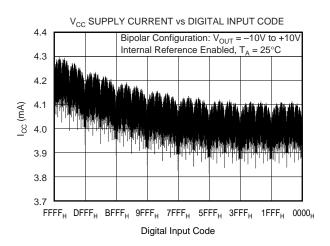




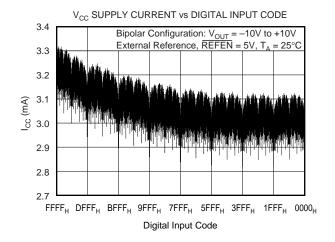


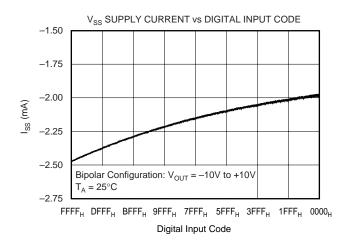


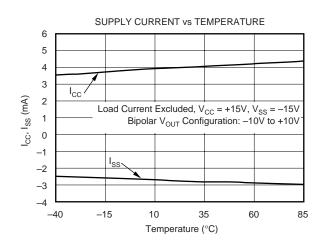


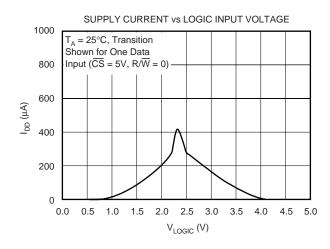


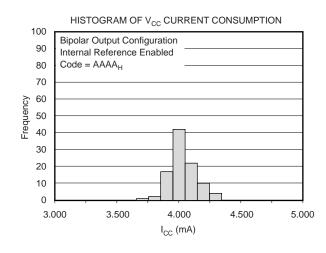


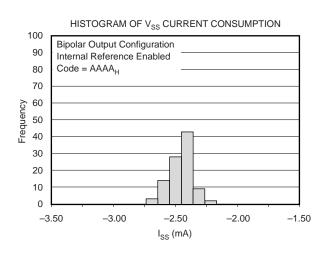


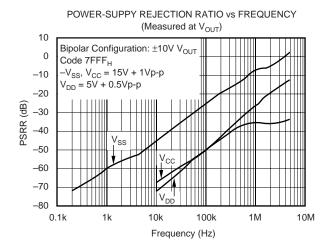


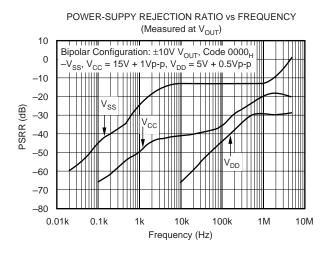


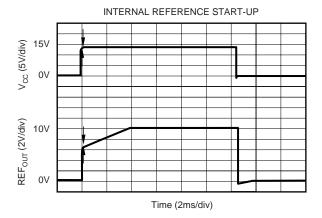


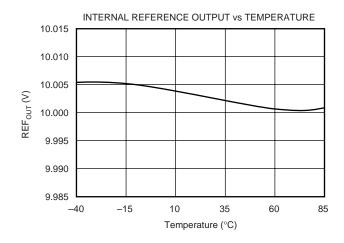


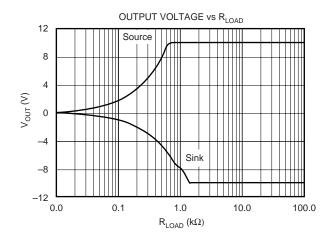


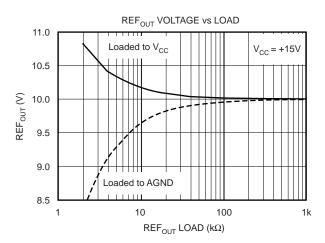




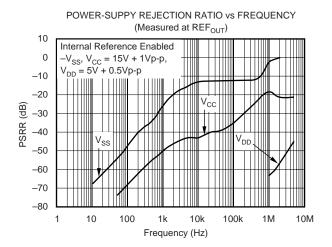


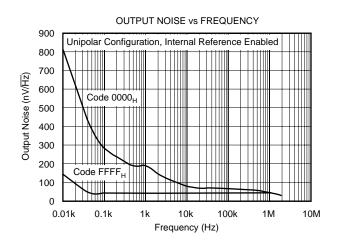


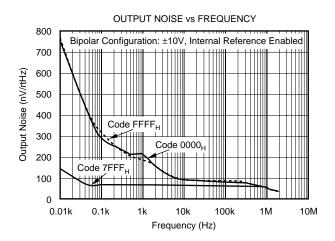


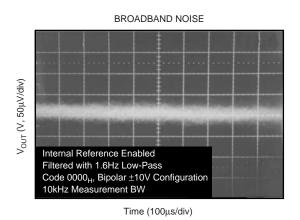


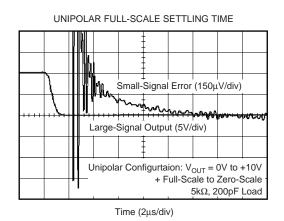


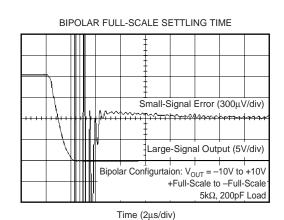






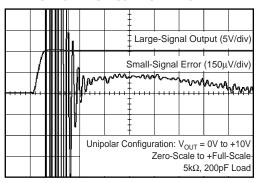






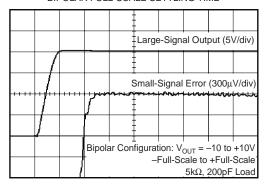
 $T_A = +25^{\circ}C$ (unless otherwise noted).

UNIPOLAR FULL-SCALE SETTLING TIME



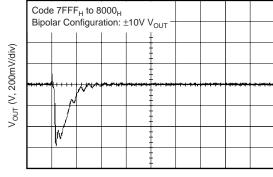
Time (2µs/div)

BIPOLAR FULL-SCALE SETTLING TIME



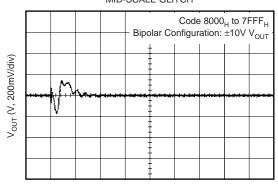
Time (2µs/div)

MID-SCALE GLITCH



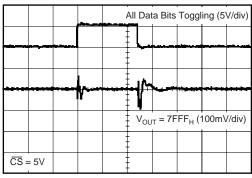
Time (1µs/div)

MID-SCALE GLITCH



Time (1µs/div)

DIGITAL FEEDTHROUGH



Time (200ns/div)



THEORY OF OPERATION

The DAC7742 is a voltage output, 16-bit DAC with a +10V built-in internal reference. The architecture is an R-2R ladder configuration with the three MSBs segmented, followed by an operational amplifier that serves as a buffer, as shown in Figure 1. The output buffer is designed to allow user-configurable output adjustments giving the DAC7742 output voltage ranges of 0V to +10V, -5V to +5V, or -10V to +10V. Please refer to Figures 2, 3, and 4 for pin configuration information.

The digital input is a parallel word made up of the 16-bit DAC code and is loaded into the DAC register using the $\overline{\text{LDAC}}$ input pin. The converter can be powered from $\pm 12 \text{V}$ to $\pm 15 \text{V}$ dual analog supplies and a +5V logic supply. The device offers a reset function, which immediately sets the DAC output voltage and DAC register to min-scale (code FFFFH) or mid-scale (code 7FFFH). The data I/O and reset functions are discussed in more detail in the following sections.

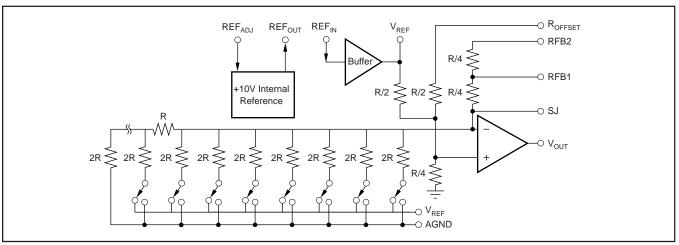


FIGURE 1. DAC7742 Architecture.

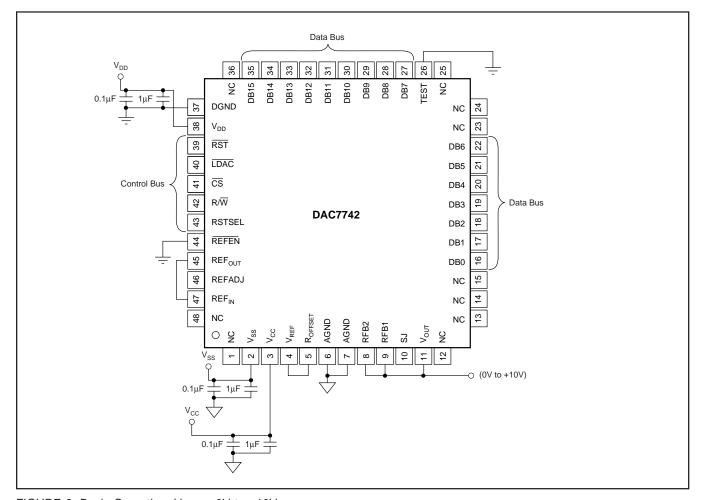


FIGURE 2. Basic Operation: $V_{OUT} = 0V$ to +10V.

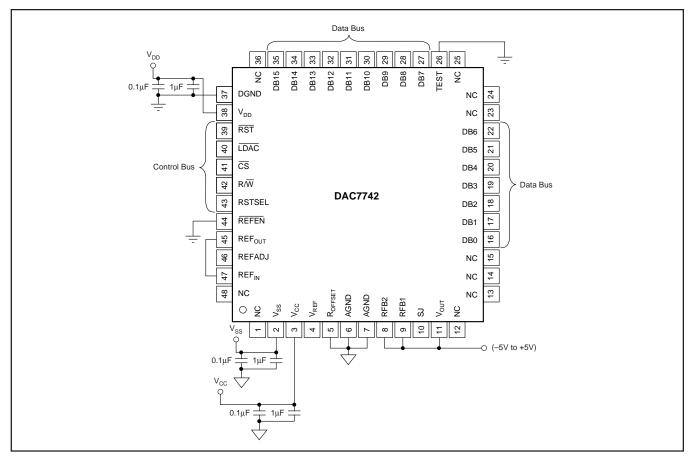


FIGURE 3. Basic Operation: $V_{OUT} = -5V$ to +5V.

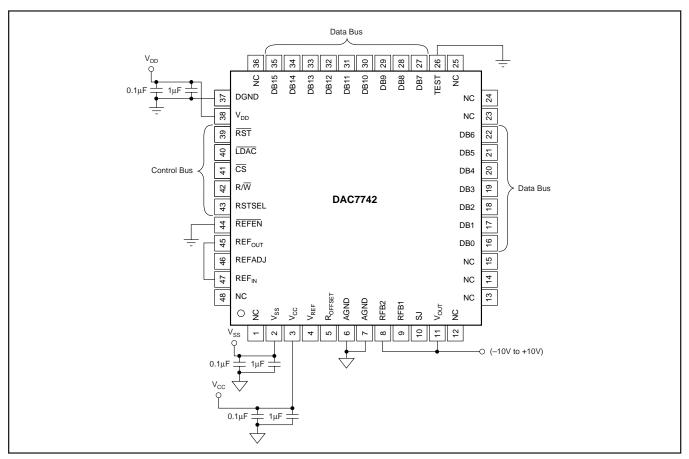


FIGURE 4. Basic Operation: $V_{OUT} = -10V$ to +10V.



ANALOG OUTPUTS

The output amplifier can swing to within 1.4V of the supply rails, specified over the -40° C to $+85^{\circ}$ C temperature range. This allows for a ± 10 V DAC voltage output operation from ± 12 V supplies with a typical 5% tolerance.

When the DAC7742 is configured for a unipolar, 0V to 10V output, a negative voltage supply is required. This is due to internal biasing of the output stage. Please refer to the "Electrical Characteristics" table for more information.

The minimum and maximum voltage output values are dependent upon the output configuration implemented and reference voltage applied to the DAC7742. Please note that $V_{\rm SS}$ (the negative power supply) must be in the range of $-4.75 \rm V$ to $-15.75 \rm V$ for unipolar operation. The voltage on $V_{\rm SS}$ sets several bias points within the converter and is required in all modes of operation. If $V_{\rm SS}$ is not in one of these two configurations, the bias values may be in error and proper operation of the device is not ensured.

Supply sequence is important in establishing correct startup of the DAC.

The digital supply (V_{DD}) needs to establish correct bias conditions before the analog supplies (V_{CC}, V_{SS}) are brought up. If the digital supply cannot be brought up first, it must come up before either analog supply $(V_{CC} \text{ or } V_{SS})$, with the preferred sequence of: V_{SS} (device substrate), V_{DD} , and then V_{CC} .

REFERENCE INPUTS

The DAC7742 provides a built-in +10V voltage reference and on-chip buffer to allow external component reference drive. To use the internal reference, $\overline{\text{REFEN}}$ must be LOW, enabling the reference circuitry of the DAC7742 (as shown in Table I) and the REF_{OUT} pin must be connected to REF_{IN} . This is the input to the on-chip reference buffer. The buffer's output is provided

REFEN	ACTION			
1	Internal Reference disabled; REF _{OUT} = High Impedance			
0	Internal Reference enabled; REF _{OUT} = +10V			

TABLE I. REFEN Action.

at the V_{REF} pin. In this configuration, V_{REF} is used to setup the DAC7742 output amplifier into one of three voltage output modes as discussed earlier. V_{REF} can also be used to drive other system components requiring an external reference.

The internal reference of the DAC7742 can be disabled when use of an external reference is desired. When using an external reference, the reference input, REF $_{\rm IN}$, can be any voltage between 4.75V (or V $_{\rm SS}$ + 14V, whichever is greater) and V $_{\rm CC}$ – 1.4V.

DIGITAL INTERFACE

Table III shows the data format for the DAC7742 and Table II illustrates the basic control logic of the device. The interface consists of a chip select input (CS), read/write control input (R/W), data inputs (DB0-DB15), and a load DAC input (LDAC). An asynchronous reset input (RST) which is active LOW, is provided to simplify start-up conditions, periodic resets, or emergency resets to a known state, depending on the status of the reset select (RSTSEL) signal. The DAC code is provided via a 16-bit parallel interface, as shown in Table II. The input word makes up the DAC code to be loaded into the data input register of the device. The data is latched into the input register on rising \overline{CS} and is loaded into the DAC register upon reception of a LOW level on the LDAC input. This action updates the analog output, V_{OUT}, to the desired value. LDAC inputs of multiple DAC7742s can be connected when a synchronized update of numerous DAC outputs is desired. Please refer to the timing section for more detailed data I/O information.

	ANALOG OUTPUT				
DIGITAL INPUT	Unipolar Configuration	Bipolar Configuration			
	Complementary Straight Binary	Complementary Offset Binary			
0xFFFF	Zero (0V)	-Full-Scale (-V _{REF} or -V _{REF} /2)			
0xFFFE	Zero + 1LSB	-Full-Scale + 1LSB			
:	:	:			
0x7FFF	1/2 Full-Scale	Bipolar Zero			
0x7FFE	1/2 Full-Scale + 1LSB	Bipolar Zero + 1LSB			
:	:	:			
0x0000	Full-Scale (V _{REF} – 1LSB)	+Full-Scale (+V _{REF} - 1LSB			
		or +V _{REF} /2 – 1LSB)			

TABLE III. DAC7742 Data Format.

CONTROL STATUS					COMMAND				
R/W	CS	RST	RSTSEL	LDAC	Input Register	DAC Register	Mode		
L	L	Н	X	Н	Write	Hold	Write Data to Input Register		
Χ	Н	Н	X	L	Hold	Write	Update DAC Register with Data from Input Register		
L	L	Н	Х	L	Transparent	Write	Write DAC Register Directly from Data Bus		
Н	L	Н	Х	H, L	Read	Hold	Read Data in Input Register		
Х	Н	Н	Х	Н	Hold	Hold	No Change		
Χ	Х	L	L	Х	Reset to Min-Scale	Reset to Min-Scale	Reset to Input and DAC Register (FFFF _H) Min-Scale		
Х	Х	L	Н	Х	Reset to Mid-Scale	Reset to Mid-Scale	Reset to Input and DAC Register (7FFF _H) Mid-Scale		

TABLE II. DAC7742 Logic Truth Table.



DAC RESET

The \overline{RST} and RSTSEL inputs control the reset of the analog output. The reset command is level triggered by a LOW signal on \overline{RST} . Once \overline{RST} is LOW, the DAC output will begin settling to the mid-scale or min-scale code depending on the state of the RSTSEL input. A HIGH value on RSTSEL will cause V_{OUT} to reset to the mid-scale code (7FFF_H) and a LOW value will reset V_{OUT} to min-scale (FFFF_H). A change in the state of the RSTSEL input while \overline{RST} is LOW will cause a corresponding change in the reset command selected internally and consequently change the output value of V_{OUT} of the DAC. Note that a valid reset signal also resets the input register of the DAC to the value specified by the state of RSTSEL.

GAIN AND OFFSET CALIBRATION

The architecture of the DAC7742 is designed in such a way as to allow for easily configurable offset and gain calibration using a minimum of external components. The DAC7742 has built-in feedback resistors and output amplifier summing points brought out of the package in order to make the absolute calibration possible. Figures 5 and 6 illustrate the relationship of offset and gain adjustments for the DAC7742 in a unipolar configuration and in a bipolar configuration, respectively.

When calibrating the DAC's output, offset should be adjusted first to avoid 1st-order interaction of adjustments. In unipolar mode, the DAC7742's offset is adjusted from code FFFF_H and for either bipolar mode, offset adjustments are made at code 7FFF_H. Gain adjustment can then be made at code 0000_H for each configuration, where the output of the DAC should be at +10V for the 0V to +10V - 1LSB or ± 10 V output range and +5V - 1LSB for the ± 5 V output range. Figure 7 shows the generalized external offset and gain adjustment circuitry using potentiometers.

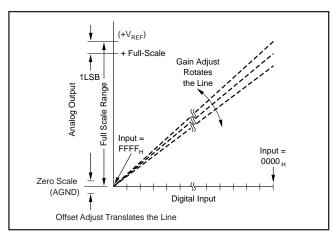


FIGURE 5. Relationship of Offset and Gain Adjustments for $V_{OLT} = 0V$ to +10V Output Configuration.

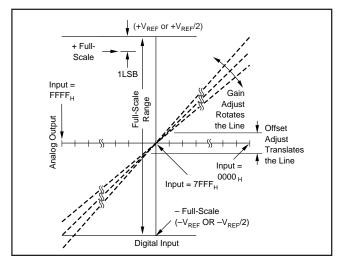


FIGURE 6. Relationship of Offset and Gain Adjustments for $V_{OUT} = -10V$ to +10V Output Configuration. (Same Theory Applies for $V_{OUT} = -5V$ to +5V.)

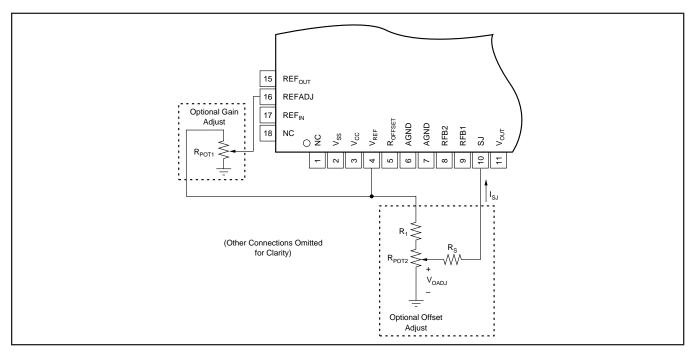


FIGURE 7. Generalized External Calibration Circuitry for Gain and Symmetrical Offset Adjustment.



OFFSET ADJUSTMENT

Offset adjustment is accomplished by introducing a small current into the summing junction (SJ) of the DAC7742. The voltage at SJ, or V_{SJ} , is dependent on the output configuration of the DAC7742. Table IV shows the required pin strapping for a given configuration and the nominal values of V_{SJ} for each output range.

REFERENCE	OUTPUT		PIN STRAPPING			
CONFIGURATION	CONFIGURATION	R _{OFFSET}	RFB1	RFB2		
Internal	0V to +10V	to V _{REF}	to V _{OUT}		+5V	
Reference	-10V to +10V	NC	NC	to V _{OUT}	+3.333V	
	-5V to +5V	to AGND	to V _{OUT}	to V _{OUT}	+2.5V	
External	0V to V _{REF}	to V _{REF}	to V _{OUT}	to V _{OUT}	V _{REF} /2	
Reference	$-V_{REF}$ to V_{REF}	NC		to V _{OUT}	V _{REF} /3	
	$-V_{REF}/2$ to $V_{REF}/2$	to AGND	to V _{OUT}	to V _{OUT}	V _{REF} /4	
NOTE: (1) Voltag	e measured at V _{SJ} fo	or a given o	configura	tion.	,	

TABLE IV. Nominal V_{SJ} vs V_{OUT} and Reference Configuration.

The current level required to adjust the DAC7742's offset can be created by using a potentiometer divider, see Figure 7. Another alternative is to use a unipolar DAC in order to apply a voltage, V_{OADJ} , to the resistor R_S . A $\pm 1.2\mu A$ current range applied to SJ will ensure offset adjustment coverage of the $\pm 0.1\%$ maximum offset specification of the DAC7742.

When in a unipolar configuration ($V_{SJ} = 5V$), only a single resistor, R_S , is needed for symmetrical offset adjustment with a 0V to 10V V_{OADJ} range. When in one of the two bipolar configurations, V_{SJ} is either +3.333v (±10V range) or +2.5V (±5V range), and circuit values chosen to match those given in Table V will provide symmetrical offset adjust. Please refer to Figure 7 for component configuration.

OUTPUT CONFIGURATION	R _{POT2}	R ₁	R _s	I _{SJ} RANGE	NOMINAL OFFSET ADJUSTMENT
0V to +10V	10k	0	2.5M	±2μA	±25mV
-10V to +10V	10k	5k	1.5M	±2.2μΑ	±55mV
-5V to +5V	10k	10k	1.5M	±1.7μA	±21mV

TABLE V. Recommended External Component Values for Symmetrical Offset Adjustment (V_{REF} = 10V).

Figure 8 illustrates the typical and minimum offset adjustment ranges provided by forcing a current at SJ for a given output voltage configuration.

GAIN ADJUSTMENT

When using the internal reference of the DAC7742, gain adjustment is performed by adjusting the device's internal reference voltage via the reference adjust pin, REFADJ. The effect of a reference voltage change on the gain of the DAC output can be seen in the generic equation (for unipolar configuration):

$$V_{OUT} = V_{REFIN} \bullet \left(\frac{\left(65535 - N\right)}{65536} \right)$$

Where N is represented in decimal format and ranges from 0 to 65535.

REFADJ can be driven by a low impedance voltage source such as a unipolar, 0V to +10V DAC or a potentiometer (less than 100k Ω), see Figure 7. Since the input impedance of REFADJ is typically $50k\Omega$, the smaller the resistance of the potentiometer, the more linear the adjustment will be. A $10k\Omega$ potentiometer is suggested if linearity of the reference adjustment is of concern.

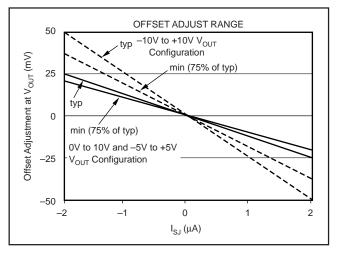


FIGURE 8. Offset Adjustment Transfer Characteristic.

When the DAC7742's internal reference is not used, gain adjustments can be made via trimming the external reference applied to the DAC at REF_{IN}. This can be accomplished through using a potentiometer, unipolar DAC, or other means of precision voltage adjustment to control the voltage presented to the DAC7742 by the external reference. Figure 9 and Table VI summarize the range of adjustment of the internal reference via REFADJ.

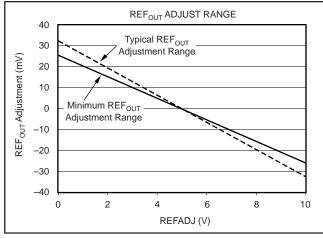


FIGURE 9. Internal Reference Adjustment Transfer Characteristic.

VOLTAGE AT REFADJ	REF _{OUT} VOLTAGE			
REFADJ = 0V	10V + 25mV (min)			
REFADJ = 5V or NC ⁽¹⁾	10V			
REFADJ = 10V	10V - 25mV (max)			
NOTE: "NC" is "Not Connected".				

TABLE VI. Minimum Internal Reference Adjustment Range.



NOISE PERFORMANCE

Increased noise performance of the DAC output can be achieved by filtering the voltage reference input to the DAC7742. Figure 10 shows a typical internal reference filter schematic. A low-pass filter applied between the REF_OUT and REF_IN pins can increase noise immunity at the DAC and output amplifier. The REF_OUT pin can source a maximum of $50\mu A$ so care should be taken in order to avoid overloading the internal reference output.

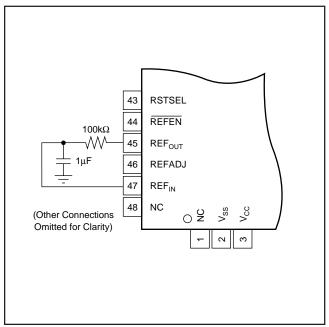


FIGURE 10. Internal Reference Filter.

LAYOUT

A precision analog component requires careful layout, adequate bypassing, and clean, well-regulated power supplies. The DAC7742 offers separate digital and analog supplies, as it will often be used in close proximity with digital logic, microcontrollers, microprocessors, and digital signal processors. The more digital logic present in the design and the higher the switching speed, the more important it will become to separate the analog and digital ground and supply planes at the device.

Since the DAC7742 has both analog and digital ground pins, return currents can be better controlled and have less effect on the DAC output error. Ideally, AGND would be connected directly to an analog ground plane and DGND to the digital ground plane. The analog ground plane would be separate from the ground connection for the digital components until they were connected at the power entry point of the system.

The voltages applied to V_{CC} and V_{SS} should be well regulated and low noise. Switching power supplies and DC/DC converters will often have high-frequency glitches or spikes riding on the output voltage. In addition, digital components can create similar high-frequency spikes as their internal logic switches states. This noise can easily couple into the DAC output voltage through various paths between the power connections and analog output.

In addition, a $1\mu F$ to $10\mu F$ bypass capacitor in parallel with a $0.1\mu F$ bypass capacitor is strongly recommended for each supply input. In some situations, additional bypassing may be required, such as a $100\mu F$ electrolytic capacitor or even a "Pi" filter made up of inductors and capacitors—all designed to essentially low-pass filter the analog supplies, removing any high frequency noise components.



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Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
DAC7742YB/250	Active	Production	LQFP (PT) 48	250 SMALL T&R	Yes	Call TI	Level-3-260C-168 HR	-40 to 85	DAC7742Y B
DAC7742YB/250.A	Active	Production	LQFP (PT) 48	250 SMALL T&R	Yes	Call TI	Level-3-260C-168 HR	-40 to 85	DAC7742Y B
DAC7742YC/250	Active	Production	LQFP (PT) 48	250 SMALL T&R	Yes	Call TI	Level-3-260C-168 HR	-40 to 85	DAC7742Y C
DAC7742YC/250.A	Active	Production	LQFP (PT) 48	250 SMALL T&R	Yes	Call TI	Level-3-260C-168 HR	-40 to 85	DAC7742Y C

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

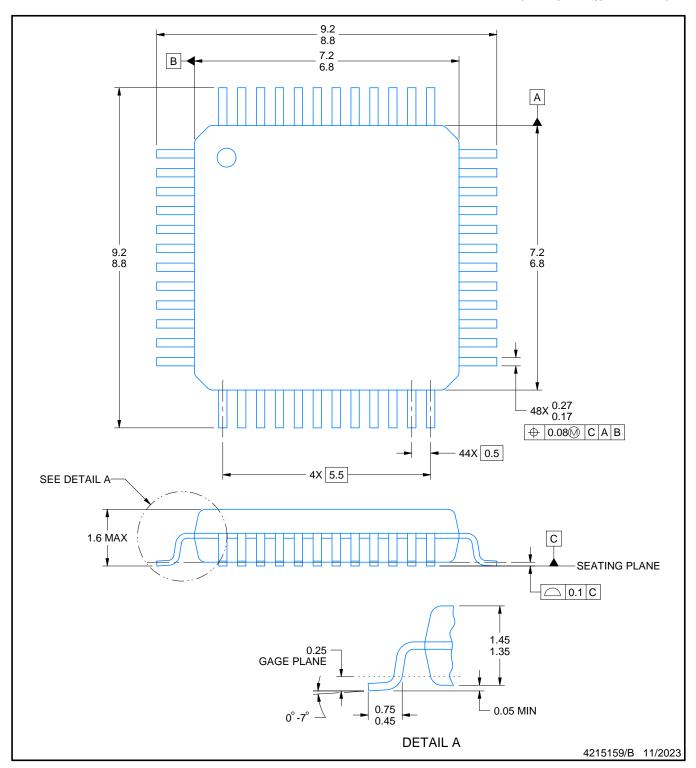


PACKAGE OPTION ADDENDUM

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LOW PROFILE QUAD FLATPACK

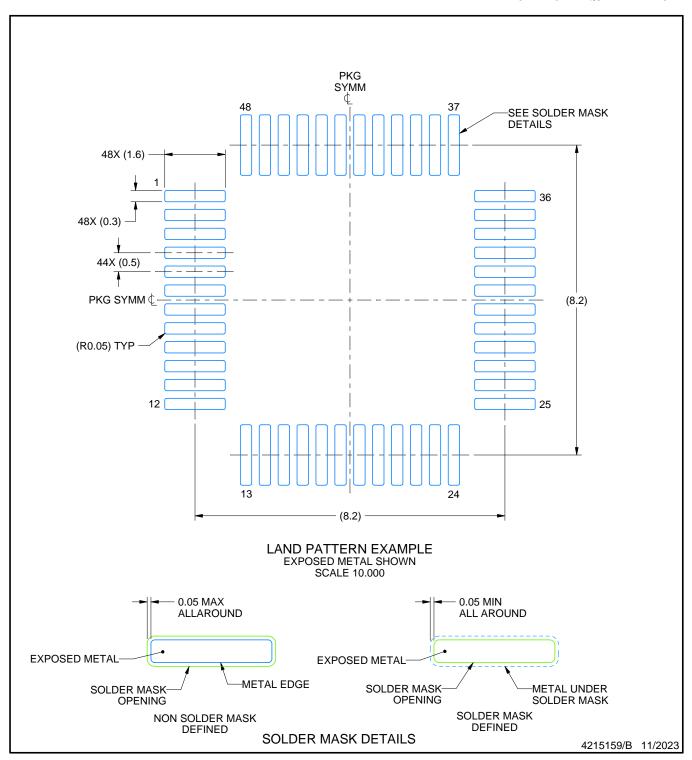


NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 Reference JEDEC registration MS-026.
 This may also be a thermally enhanced plastic package with leads conected to the die pads.



LOW PROFILE QUAD FLATPACK

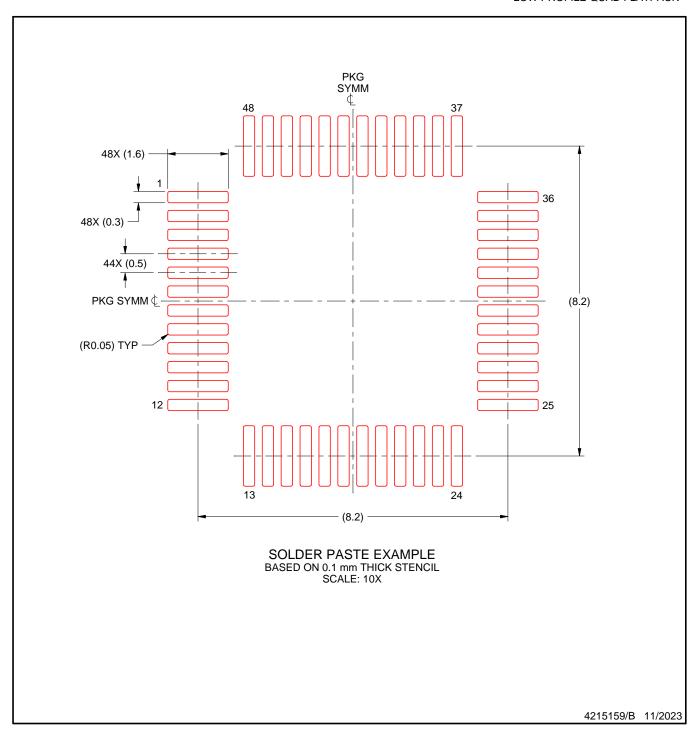


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



LOW PROFILE QUAD FLATPACK



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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